

Orbotech Diamond[™] 10M/10MXL

Solder Mask at its Best

Orbotech Diamond 10M/10MXL

Orbotech Diamond 10M/10MXL is an advanced high-capacity digital imaging (DI) solution for a wide variety of solder mask (SM) applications. Designed for white and other colors of solder masks, the field-proven Orbotech Diamond 10M/10MXL is a high-end mass production solution that delivers high-quality imaging and high throughput for the most complex designs. Powered by KLA's proprietary SolderFast™ technology, Orbotech Diamond 10M/10MXL raises the DI bar for solder mask applications, enhancing imaging accuracy while decreasing total cost of ownership (TCO).



Benefits

High-Quality Imaging

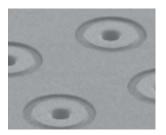
- High-quality imaging of white and other colors of solder mask
- Multi-wavelength spectrum for high-quality sidewalls and excellent surface quality
- Significantly reduced undercuts for white solder masks
- High depth-of-focus (DOF) for challenging topographies

High Capacity, High Throughput

- Patented, high power illumination source
- One-pass exposure for uniform imaging of the full panel area in a single scan
- Dual-table transport mechanism for optimal imaging time
- On-the-fly target recognition and acquisition capabilities

Outstanding Imaging Accuracy

- Registration accuracy as fine as ±10μm
- Advanced scaling modes for challenging panel distortions



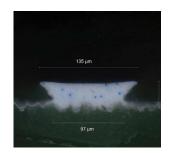
High-qualty SM imaging, no residue on vias



Orbotech Diamond 10M White SM Dam with minimal undercut



High registration accuracy

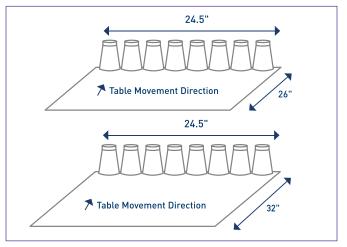


Other SM DI solution
White SM Dam with
severe undercut

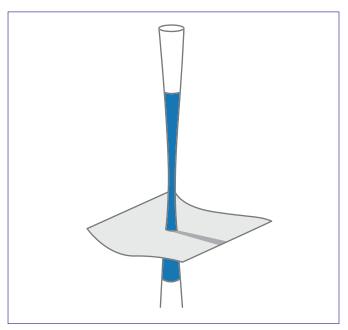




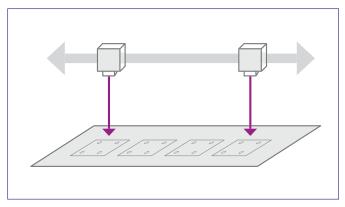
High-Quality Imaging and High Throughput



One pass printing for high throughput, high uniformity and no stitiching

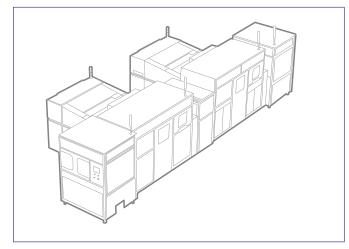


High depth-of-focus (DOF) for challenging topographies

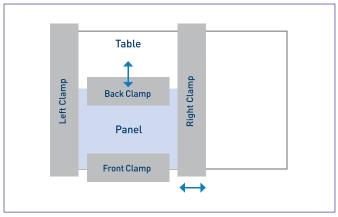


On-the-fly target recognition and acquisition

High-Capacity Mass Production Solution



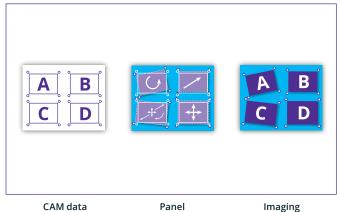
Automation-ready solution



Clamping

Outstanding Imaging Accuracy

Advanced scaling modes and algorithms for challenging panel distortions include auto scaling, partial scaling and non-linear scaling



CAM data



Specifications

Orbotech Diamond 10M

Orbotech Diamond 10MXL

Minimum SRO*	White SM - 100μm, Non-white SM - 75μm	
Minimum Dam Size*	White SM - 75μm, Non-white SM - 50μm	
Registration Accuracy**	±10μm	
Maximum Panel Area (X/Y)	25" x 26" (635mm x 660mm)	25" x 32" (635mm x 812mm)
Maximum Panel Area (X/Y) with Clamping	24.5" x 23" (622mm x 584mm)	24.5" x 30" (622mm x 762mm)***
Maximum Exposure Area (X/Y)	24.5" x 26" (622mm x 660mm)	24.5" x 32" (622mm x 812mm)
Maximum Exposure Area (X/Y) with Clamping (4 clamps)	24" x 22.5" (609mm x 571mm)	24" x 29.5" (609mm x 749mm)
Exposure Energy Range	50-2,200mJ/cm ²	
Dimensions	Height: 1,960mm Depth: 3,226mm Width: 1,900mm	Height: 1,960mm Depth: 3,315mm Width: 1,900mm
Weight	5,000Kg	
Clamping	Optional	
Application	Solder mask exposure	

^{*}Dependent on solder resist type and process

^{**} All values are 3σ *** 24.5" x 32" (622mm x 812mm) with 3 clamps (instead of 4)

The above specifications are subject to change without notification.